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## NP0G3D3

## Silicon PNP epitaxial planar type (Tr1) Silicon NPN epitaxial planar type (Tr2)

### For digital circuits

#### ■ Features

- Two elements incorporated into one package
- Suitable for high-density mounting and downsizing of the equipment
- Automatic insertion with the taping is possible

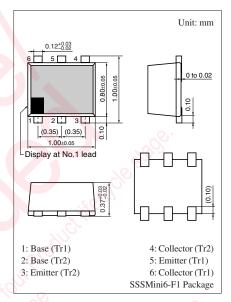
### ■ Basic Part Number

• UNR31A3 + UNR32AT

### ■ Absolute Maximum Ratings $T_a = 25$ °C

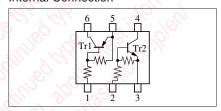
	Parameter	Symbol	Rating	Unit	
Tr1	Collector-base voltage	$V_{CBO}$	-50	V	
	(Emitter open)				
	Collector-emitter voltage	V <sub>CEO</sub>	-50	V	
	(Base open)				
	Collector current	$I_{C}$	-80	mA (	
Tr2	Collector-base voltage	V <sub>CBO</sub>	50	V	
	(Emitter open)				
	Collector-emitter voltage	V <sub>CEO</sub>	50	P V	
	(Base open)				
	Collector current	$I_{C}$	80	mA	
Overall	Total power dissipation *	$P_{T}$	125	mW	
	Junction temperature	Tj	125	0°C }	
	Storage temperature	$T_{stg}$	-55 to +125	°C O	

Note) \*: Measuring on substrate at 17 mm × 10 mm × 1 mm



Marking Symbol: 3H

### Internal Connection



### ■ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

#### • Tr1

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	$I_C = -10 \ \mu A, \ I_E = 0$	-50			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = -2 \text{ mA}, I_B = 0$	-50			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = -50 \text{ V}, I_E = 0$			- 0.1	μΑ
Collector-emitter cutoff current (Base open)	I <sub>CEO</sub>	$V_{CE} = -50 \text{ V}, I_B = 0$			- 0.5	μΑ
Emitter-base cutoff current (Collector open)	$I_{EBO}$	$V_{EB} = -6 \text{ V}, I_C = 0$			- 0.1	mA
Forward current transfer ratio	h <sub>FE</sub>	$V_{CE} = -10 \text{ V}, I_{C} = -5 \text{ mA}$	80			_
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = -10 \text{ mA}, I_B = -0.3 \text{ mA}$			- 0.25	V
Output voltage high-level	V <sub>OH</sub>	$V_{CC} = -5 \text{ V}, V_B = -0.5 \text{ V}, R_L = 1 \text{ k}\Omega$	-4.9			V
Output voltage low-level	V <sub>OL</sub>	$V_{CC} = -5 \text{ V}, V_{B} = -3.5 \text{ V}, R_{L} = 1 \text{ k}\Omega$			-0.2	V
Input resistance	R <sub>1</sub>		-30%	47	+30%	kΩ
Resistance ratio	R <sub>1</sub> / R <sub>2</sub>		0.8	1.0	1.2	_
Transition frequency	$f_{T}$	$V_{CB} = -10 \text{ V}, I_E = 1 \text{ mA}, f = 200 \text{ MHz}$		80		MHz

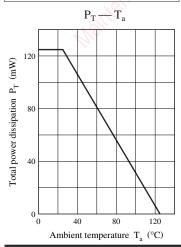
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

### • Tr2

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	$I_{\rm C} = 10  \mu A,  I_{\rm E} = 0$	50			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = 2 \text{ mA}, I_B = 0$	50			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 50 \text{ V}, I_{E} = 0$			0.1	μA
Collector-emitter cutoff current (Base open)	I <sub>CEO</sub>	$V_{CE} = 50 \text{ V}, I_{B} = 0$	7		0.5	μΑ
Emitter-base cutoff current (Collector open)	$I_{EBO}$	$V_{EB} = 6 \text{ V}, I_C = 0$	082		0.2	mA
Forward current transfer ratio	$h_{FE}$	$V_{CE} = 10 \text{ V}, I_{C} = 5 \text{ mA}$	80	1	400	<i></i>
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = 10 \text{ mA}, I_B = 0.3 \text{ mA}$	100	×62,	0.25	V
Output voltage high-level	V <sub>OH</sub>	$V_{CC} = 5 \text{ V}, V_B = 0.5 \text{ V}, R_L = 1 \text{ k}\Omega$	4.9	9,	i i	V
Output voltage low-level	V <sub>OL</sub>	$V_{CC} = 5 \text{ V}, V_B = 2.5 \text{ V}, R_L = 1 \text{ k}\Omega$			0.2	V
Input resistance	$R_1$	Our We Plan Ville	-30%	22	+30%	kΩ
Resistance ratio	$R_1 / R_2$	180 CO 182	10),	0.47		_
Transition frequency	$f_T$	$V_{CB} = 10 \text{ V}, I_E = -2 \text{ mA}, f = 200 \text{ MHz}$	7.7	150		MHz

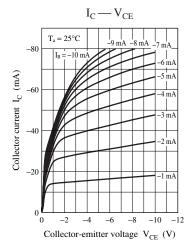
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

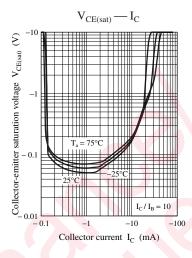
### Common characteristics chart

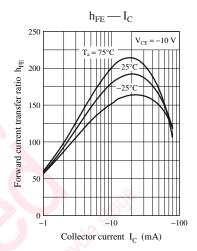


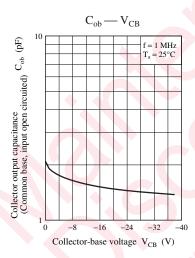
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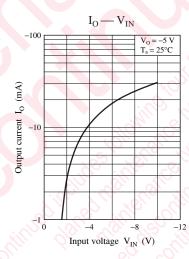
### Characteristics charts of Tr1

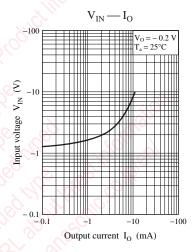






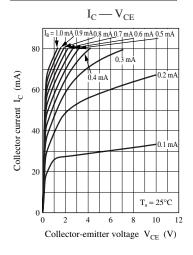


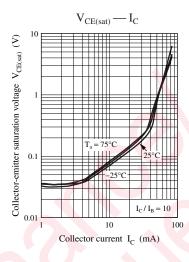


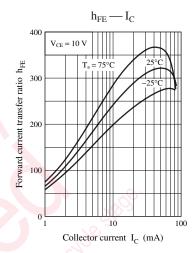


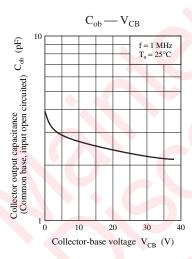
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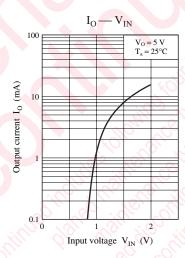
### Characteristics charts of Tr2

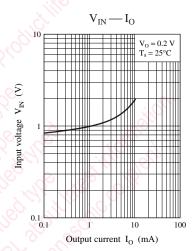












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